



**Spec No.: DS70-2001-027** Effective Date: 06/17/2016

Revision: D

**LITE-ON DCC** 

**RELEASE** 

BNS-OD-FC001/A4



### 1. DESCRIPTION

#### 1.1 Features

- Isolation voltage between input and output V<sub>iso</sub>: 5,000V<sub>rms</sub>
- 6pin DIP zero-cross optoisolators triac driver output
- High repetitive peak off-state voltage VDRM : Min. 800V
- High critical rate of rise of off-state voltage( dV/dt : MIN. 1000V / μs )
- Dual-in-line package: MOC3081 / MOC3082 / MOC3083
- Wide lead spacing package: MOC3081M / MOC3082M / MOC3083M
- Surface mounting package: MOC3081S / MOC3082S / MOC3083S
- Tape and reel packaging: MOC3081S-TA1 / MOC3082S-TA1 / MOC3083S-TA1
- Safety approval

UL 1577

cUL CA5A

VDE DIN EN60747-5-5 (VDE 0884-5)

- RoHS Compliance
  - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- MSL class1

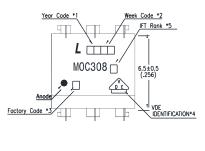
### **1.2 Applications**

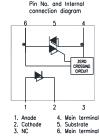
- AC Motor Drives
- AC Motor Starters
- E.M. Contactors
- Lighting Controls
- Solenoid/Valve Controls
- Solid State Relays
- Static Power Switches
- Temperature Controls

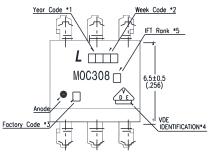


### 2. PACKAGE DIMENSIONS

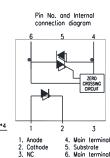
#### 2.1 MOC308X

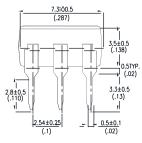


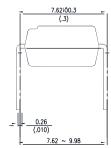


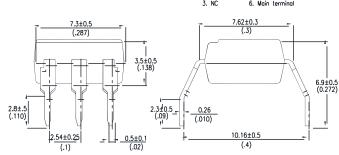


2.2 MOC308XM

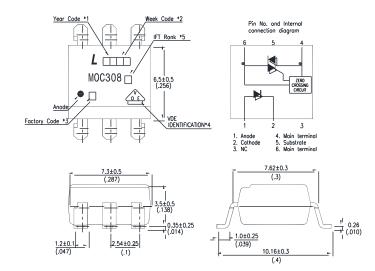








### 2.3 MOC308XS



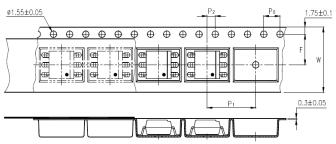
### Notes:

- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. VDE option
- 5. I<sub>FT</sub> rank
- \* Dimensions are in Millimeters and (Inches).

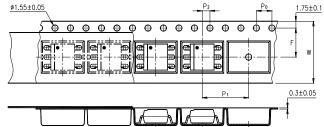


## 3. TAPING DIMENSIONS

### 3.1 MOC308XS-TA



### 3.2 MOC308XS-TA1



Description	Symbol	Dimension in mm (inch)		
Tape wide	W	16±0.3 (0.63)		
Pitch of sprocket holes	P <sub>0</sub>	4±0.1 (0.15)		
Distance of compartment	F	7.5±0.1 (0.295)		
Distance of compartment	P <sub>2</sub>	2±0.1 (0.079)		
Distance of compartment to compartment	P <sub>1</sub>	12±0.1 (0.472)		

#### 3.3 Quantities Per Reel

Package Type	MOC308XS series
Quantities (pcs)	1000



### 4. RATING AND CHARACTERISTICS

### 4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	I <sub>F</sub>	50	mA
lanut	Reverse Voltage	$V_{R}$	6	V
Input	Junction Temperature	$T_J$	125	°C
	Power Dissipation	Р	120	mW
Off-State Output Terminal Voltage		$V_{DRM}$	800	V
	On-State RMS Current	I <sub>D(RMS)</sub>	100	mA
Output	Peak Repetitive Surge Current ( PW=1ms, 120pps )	I <sub>TSM</sub>	1	А
	Junction Temperature	Τ <sub>J</sub>	125	°C
	Collector Power Dissipation	Pc	150	mW
	Total Power Dissipation	P <sub>tot</sub>	250	mW
1.	Isolation Voltage	$V_{\rm iso}$	5000	$V_{rms}$
	Operating Temperature	$T_{opr}$	-40 ~ +110	°C
	Storage Temperature	$T_{stg}$	-55 ~ +150	°C
2.	Soldering Temperature	$T_{sol}$	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



#### 4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

Parameter			Symb	Min.	Тур.	Max.	Unit	Test Condition	
1	Forward Voltage			V <sub>F</sub>	_	1.2	1.4	٧	I <sub>F</sub> =20mA
Input		Reverse Current		I <sub>R</sub>	_	0.05	10	μА	V <sub>R</sub> =6V
	Peak Blocking Current, Either  1 Direction		I <sub>DRM</sub>	_	_	500	nA	V <sub>DRM</sub> = 800V	
Output Peak On-State Vo		Peak On-State Voltage Direction	e, Either	$V_{TM}$	_	_	3.0	V	I <sub>TM</sub> =100 mA Peak
	Critical rate of Rise of Off-State  Voltage		dv/dt	1000	_	_	V/μs	Vin=240Vrms	
Couple	Led Trigger Current,  Current Required to  Latch Output, Either  Direction	MOC3061		_	_	15			
		•	MOC3062	I <sub>FT</sub>	_	_	10	mA	Main Terminal Voltage = 3V
		MOC3063		_	_	5			
	Holding Current, Either Direction		l <sub>Η</sub>	_	400	_	μА		
ZERO CROSSING		Inhibit Voltage		V <sub>INH</sub>	_	5	20	Volts	I <sub>F</sub> =Rated I <sub>FT</sub> , MT1-MT2 Voltage above which device will not trigger.
5.1000m10	Leakage in Inhibited State		I <sub>DRM2</sub>	_	_	500	μА	$I_F$ = Rated $I_{FT}$ , Rated $V_{DRM}$ , Off State	

<sup>\*1.</sup> Test voltage must be applied within dv/dt rating.

<sup>\*2.</sup> This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.

<sup>\*3.</sup> All devices are guaranteed to trigger at an I<sub>F</sub> value less than or equal to max I<sub>FT</sub>. Therefore, recommended operating I<sub>F</sub> lies between max I<sub>FT</sub>, 15 mA for MOC3081, 10 mA for MOC3082, 5 mA for MOC3083, and absolute max I<sub>F</sub> (50mA).



## 5. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

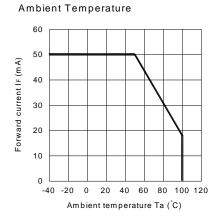


Fig.2 On-state Current vs. Ambient Temperature

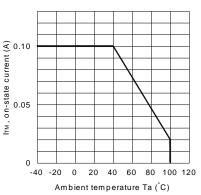


Fig.3 Minimum Trigger Current vs. Ambient Temperature

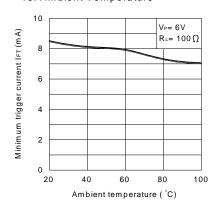


Fig.4 Forward Current vs. Forward Voltage

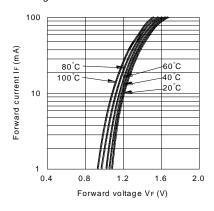


Fig.5 On-state Voltage vs. Ambient Temperature

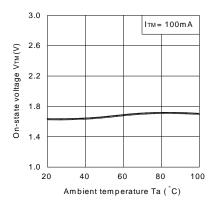


Fig.6 Holding Current vs.

Ambient Temperature

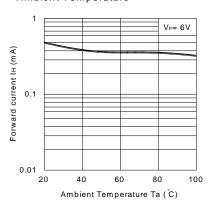




Fig. 7 Repetitive Peak Off-state Current vs. Temperature

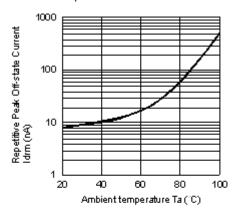
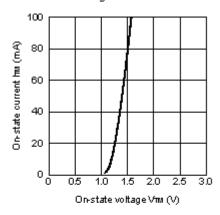
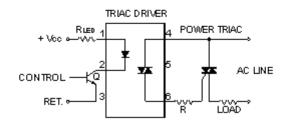


Fig. 8 On-state Current vs.

On-state Voltage



#### Basic Driver Circuit



Rues=(Voo-Vr LED-VsaQ)/ Irm R= Vp AC line/Iran

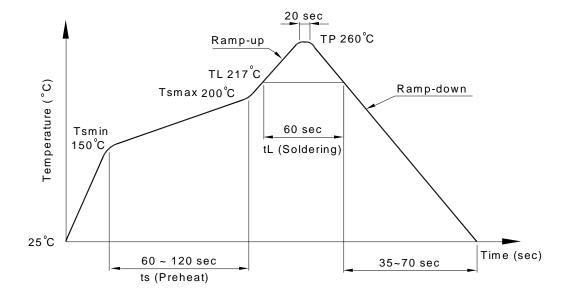


### 6. TEMPERATURE PROFILE OF SOLDERING

### 6.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three

Profile item	Conditions			
Preheat				
- Temperature Min (T <sub>Smin</sub> )	150°C			
- Temperature Max (T <sub>Smax</sub> )	200°C			
- Time (min to max) (ts)	90±30 sec			
Soldering zone				
- Temperature (T <sub>L</sub> )	217°C			
- Time (t∟)	60 sec			
Peak Temperature (T <sub>P</sub> )	260°C			
Ramp-up rate	3°C / sec max.			
Ramp-down rate	3~6°C / sec			







### 6.2 Wave soldering (JEDEC22A111 compliant)

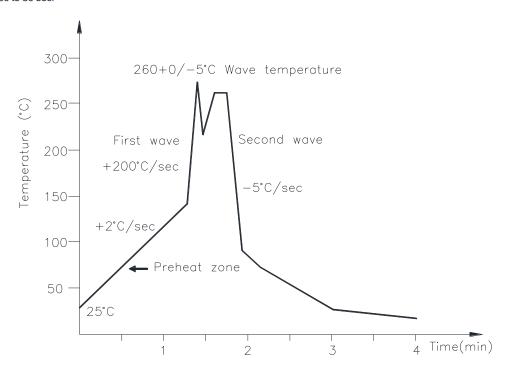
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



### 6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

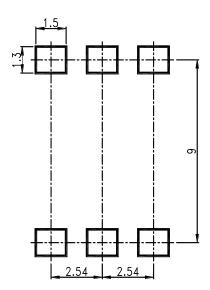
Time: 3 sec max.





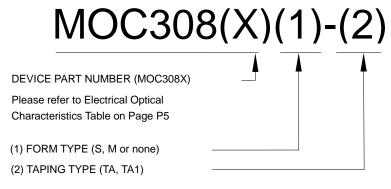
## 7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm

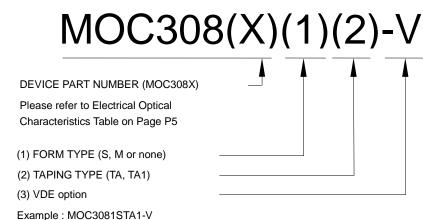




#### 8. NAMING RULE



Example : MOC3081S-TA1



#### 9. NOTES

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- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.

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